



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com

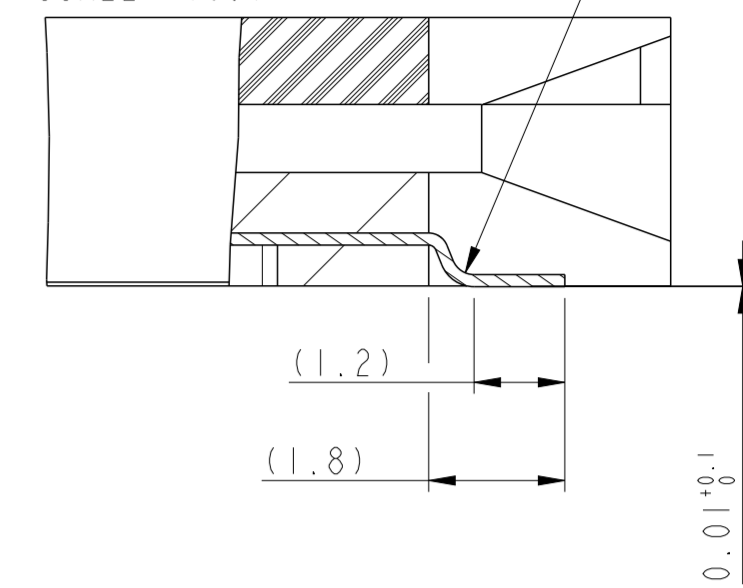
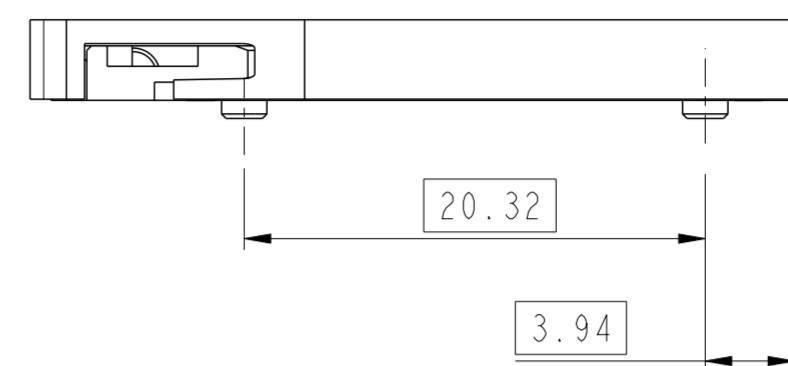
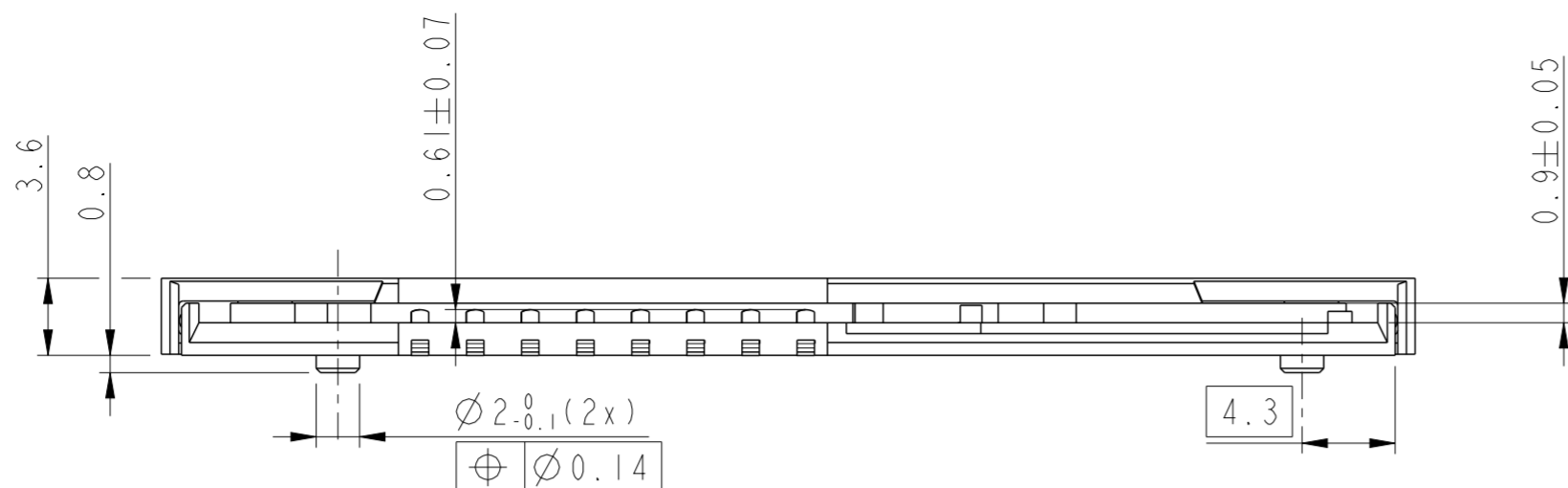
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



LEAD FREE CATALOGUE NUMBER

7312P0235A13LF

SECTION A-A
SCALE 10:1



DESCRIPTION
Connector especially designed for SMT technology
EMV compatible and in accordance with ISO 7816-2

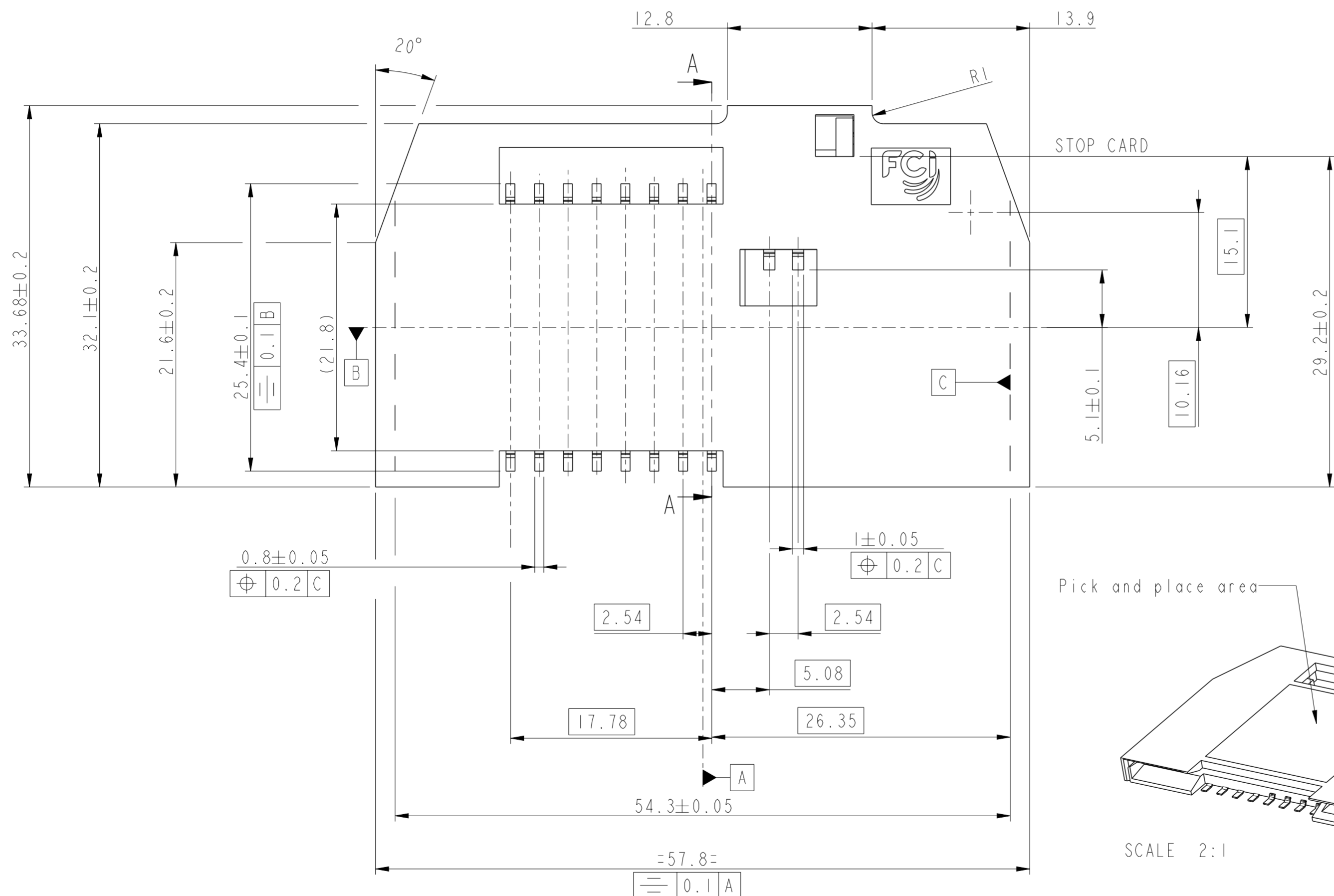
MECHANICAL
Contacts force : between 0.2N-0.5N
Durability : 100000 cycles
Insertion force : 10N max
Extraction force : 3N min

ELECTRICAL
Insulation resistance : 1000MΩ
Dielectric withstand voltage between card contacts and detection switch : 1000 Vrms
contact resistance:100 miliohms
Current carrying : min 10 microA max 1A

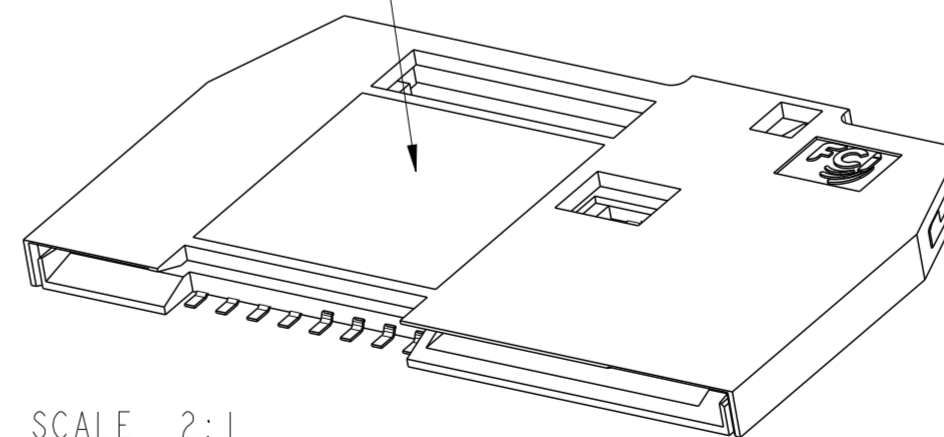
SWITCH
Contact closed : contact resistance 100mΩ
Open contact : voltage proof 300Vms

MATERIAL
Contacts : copper alloy
Plating : Gold / Equivalent PdNi over Nickel on contact area
Solder falls : Sn bare edge allowed
Housing : self extinguishing, Thermoplastic
UL94-V0 rated

ENVIRONMENT
Storage temperature : -40°C, +85°C
Operating temperature : -20°C, +70°C
Packaging : Tray
Compatible reflow soldering process



Pick and place area



SCALE 2:1

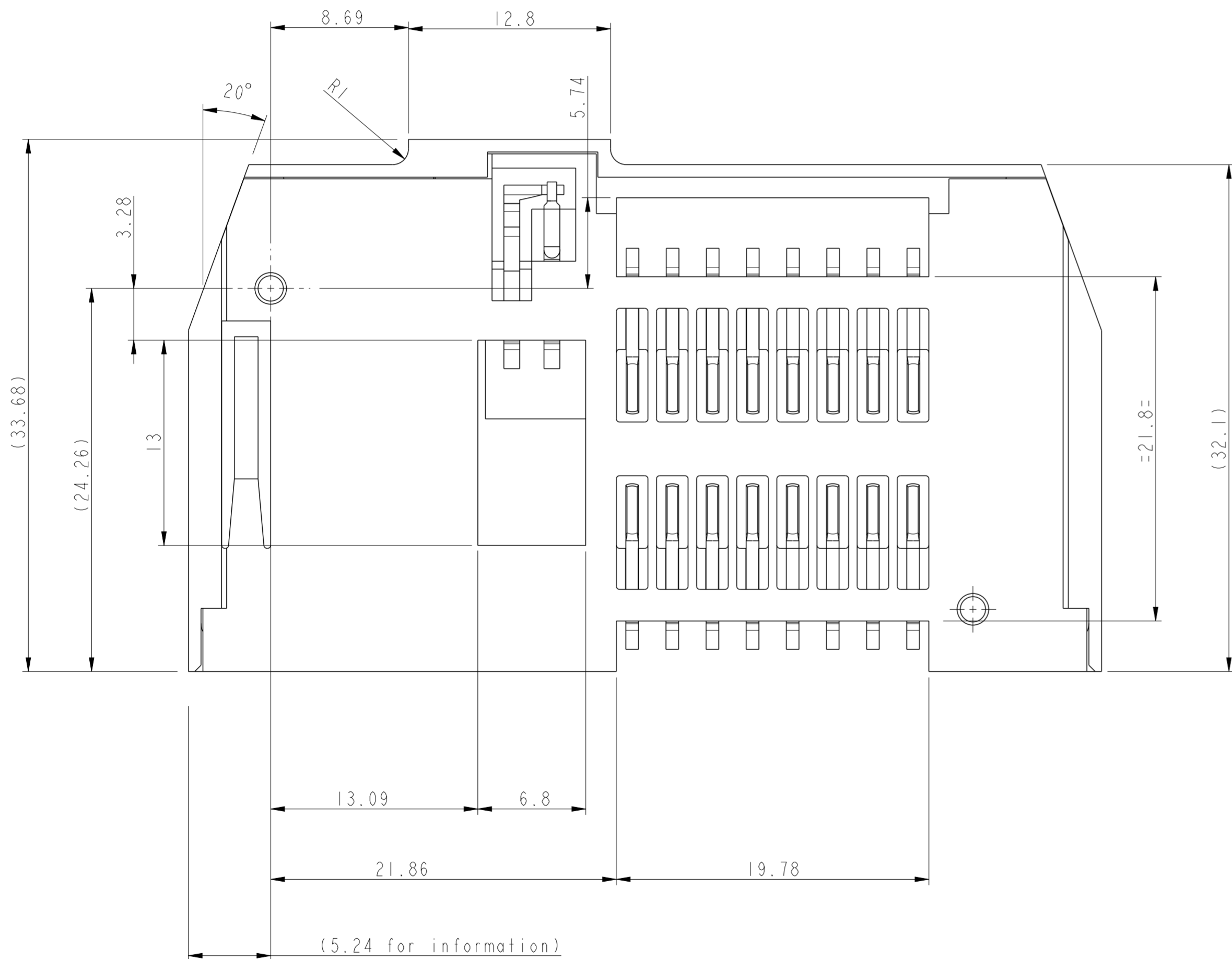
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A	LS2030	PR1	2002/04/26
B	--	--	--
C	LS05-0047	LGO	2005/06/08
D	LS05-0059	HLE	2005/06/30
E	LS06-0208	HLE	2006/12/12
F	108-0035	RPK	2008/03/07
G	109-0239	RPK	2009/10/30

www.fciconnect.com		surface -- ✓	tolerance std	projection	mm
		ISO 1302	ISO 406 ISO 1101	⊕	←→
TOLERANCES UNLESS OTHERWISE SPECIFIED					
Dr	LEGRAND	1996/08/26	ANGULAR	LINEAR	size A2
Eng	TISSERAND	1996/08/26	0.X	±0.3	Scale 3:1
Chr	RAMESH P K	2007/02/26	0.XX	±0.1	
Appr	SUDHIR V	2007/02/26	0.XXX	±0.05	ECN 109-0239
Product family			MOBILE I/O	Spec ref	--
CHIP CARD CONNECTOR				kg no	Rev.
TYPE : P02 (16cts with cover)				VJW53665	F
catalog no				7312P0235A13	sheet 1 of 2

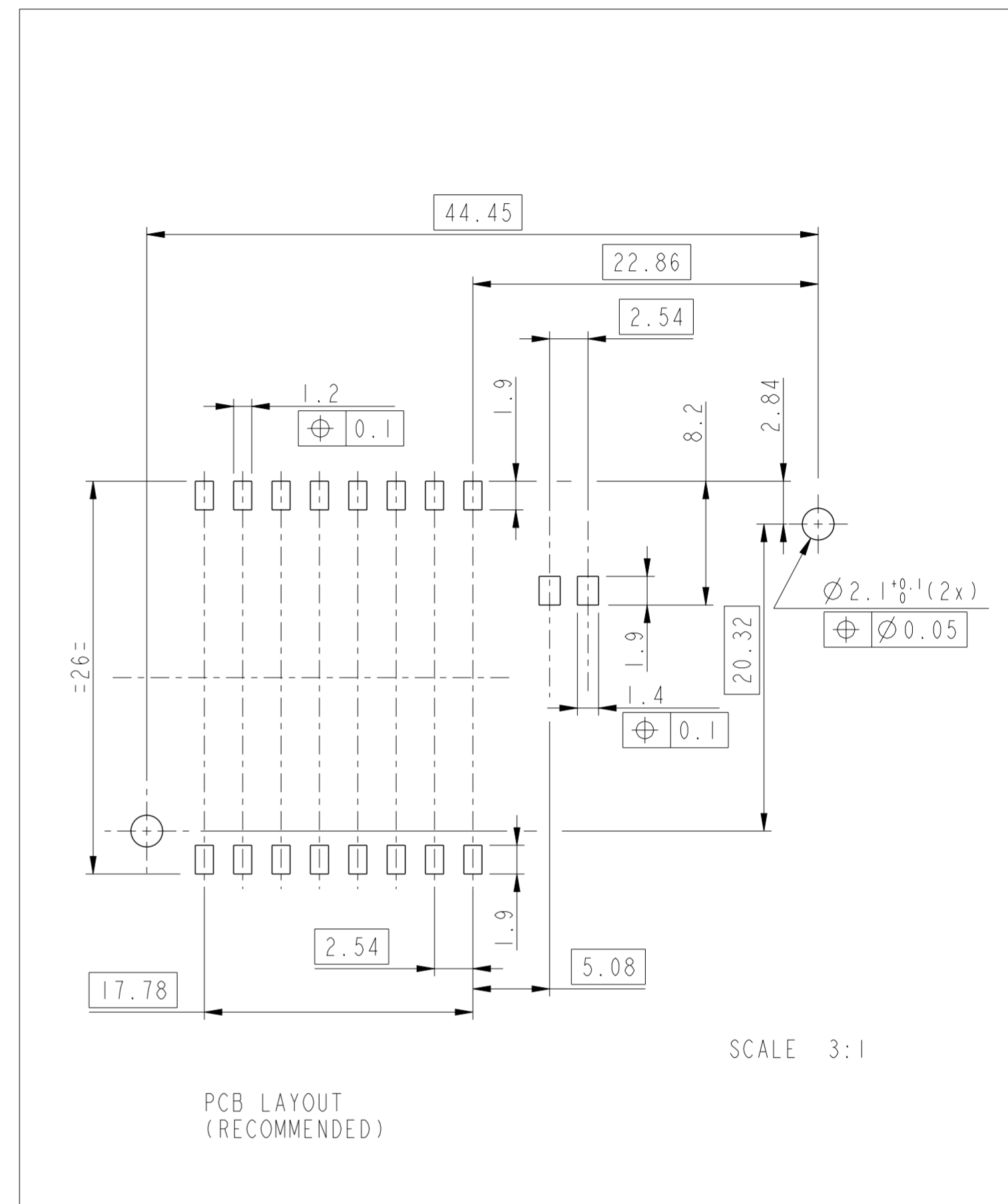
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LEAD FREE CATALOGUE NUMBER

7312P0235A13LF



LAYOUT FOR KEEP OUT ZONE
(CONNECTOR SIDE)



NOTE: RoHS INFORMATIONS

- The "LF" products meet European Union Directives and other country regulations as described in GS-22-008.
- The housing will withstand exposure to 260°C peak temperature for 30 seconds in a convection, infra-red or vapor reflow oven. See Application notes/procedures, if they are available.
- Packaging spec: see GS-14-920

www.fciconnect.com		surface -- ✓	tolerance std ISO 1302	ISO 406	ISO 1101	projection	mm
		TOLERANCES UNLESS OTHERWISE SPECIFIED					
Dr	LEGRAND	1996/08/26	ANGULAR	0.x	±0.3	size	Scale
Eng	TISSERAND	1996/08/26	LINEAR	0.xx	±0.1	A2	4:1
Chr	RAMESH P K	2007/02/26	0° ±2°	0.xxx	±0.05	ECN	109-0239
Appr	SUDHIR V	2007/02/26	Product family	MOBILE I/O		Spec ref	--
		TITLE: CHIP CARD CONNECTOR			dwg no	VJW53665	
		TYPE: P02 (16cts with cover)			Rev.	F	
		catalog no			7312P0235A13		CUSTOMER
					sheet 2 of 2		